

IN THE SPECIFICATION:

Please replace paragraph number [0001] with the following rewritten paragraph:

[0001] This application is a continuation of application Serial No. 10/121,851, filed April 11, 2002, ~~pending now U.S. Patent 6,677,671, issued January 13, 2004~~, which is a continuation of application Serial No. 09/420,672, filed October 19, 1999, now U.S. Patent 6,445,063, issued September 3, 2002, which is a divisional of application Serial No. 09/036,662, filed March 9, 1998, now U.S. Patent 6,207,474, issued March 27, 2001.

Please replace paragraph number [0037] with the following rewritten paragraph:

[0037] Referring to FIG. 3, multiconductor insulating assembly tape 42 includes conductors (collectively conductors 50 (~~FIG-FIGS.~~ 4A, 4B)) having conductive sections that interface with terminals 30A, 30B, 30C, and 30D, and with multiconductor port 36. The nature of these sections depends on the structure and shape of such terminals, the structure of multiconductor port 36, and means of keeping multiconductor insulating assembly tape 42 stationary with respect to the individual IC devices 14A-14D and multiconductor port 36.

Please replace paragraph number [0053] with the following rewritten paragraph:

[0053] Referring to drawing FIG. 13B, multiconductor epoxy assembly 102 includes a plurality of conductors 102, each formed of suitable well known conductive epoxy material. Multistrand insulating epoxy assembly 104 includes a plurality of strips of nonconductive epoxy material 114 located between the conductors 102'. Conductors 102', like conductors 50 may be injected into, bombarded on, or otherwise adhered to the nonconductive epoxy material 114 forming multistrand insulating epoxy assembly 104. Multiple layers of conductors may also be applied to or into nonconductive epoxy material 114, such as is the case where corresponding terminals (e.g., terminals 30A-2, 30B-2, 30C-2, and 30D-2) are not to receive the same signal. The base epoxy material of multistrand insulating epoxy assembly 104 may be substantially the

same epoxy material as or somewhat different from the base epoxy material of multiconductor
epoxy assembly 102.